




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F722IET6	E01T*452ESXA	A	9991	2016-10-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	1650.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	24X24X1.4	176	L bend	
Comment	Package: 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name		E01T*452ESXA					
note : Substance present with less 0.001mg will not be declared in this document													
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	14.713	mg	supplier	die	Silicon (Si)	7440-21-3		13.738	mg	933732	8326	
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.068	mg	4622	41	
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.443	mg	30109	268	
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	68	1	
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		0.062	mg	4214	38	
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.199	mg	13525	121	
Die				supplier	Passivation	Silicon Nitride	12033-89-5		0.052	mg	3534	32	
Die				supplier	Passivation	Silicon Oxide	7631-86-9		0.150	mg	10195	91	
Mold Compound (Sumitomo G631H)	Other inorganic materials	1143.416	mg	supplier	Molding Compound	Epoxy Resin A	Trade secret		29.800	mg	26062	18061	
Mold Compound (Sumitomo G631H)				supplier	Molding Compound	Epoxy Resin B	Trade secret		29.800	mg	26062	18061	
Mold Compound (Sumitomo G631H)				supplier	Molding Compound	Phenol Resin	Trade secret		54.500	mg	47664	33030	
Mold Compound (Sumitomo G631H)				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		899.856	mg	786989	545367	
Mold Compound (Sumitomo G631H)				supplier	Molding Compound	Silica(Amorphous) B	76361-86-9		126.030	mg	110222	76382	
Mold Compound (Sumitomo G631H)				supplier	Molding Compound	Carbon black	1333-86-4		3.430	mg	3000	2079	
Leadframe (C7025)	Other inorganic materials	465.301	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		440.407	mg	946500	266914	
Leadframe (C7025)				supplier	Leadframe	Nickel (Ni)	7440-02-0		14.890	mg	32000	9024	
Leadframe (C7025)				supplier	Leadframe	Silicon (Si)	7440-21-3		3.373	mg	7250	2045	
Leadframe (C7025)				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.814	mg	1750	494	
Leadframe (C7025)				supplier	Leadframe	Silver (Ag)	7440-22-4		5.816	mg	12500	3525	
Die Attach (YIZ 8143)	Other inorganic materials	3.720	mg	supplier	Die Attach	Silver Flake	7440-22-4		2.883	mg	775000	1747	
Die Attach (YIZ 8143)				supplier	Die Attach	Epoxy Acylate	15625-89-5		0.186	mg	50000	113	
Die Attach (YIZ 8143)				supplier	Die Attach	Substiyuted Polyamine	68490-66-4		0.056	mg	15000	34	
Die Attach (YIZ 8143)				supplier	Die Attach	Bisphenol F	28064-14-4		0.372	mg	100000	225	
Die Attach (YIZ 8143)				supplier	Die Attach	2-Ethylhexyl glycidyl ether	2461-15-6		0.223	mg	60000	135	
Wire (Au)	Other inorganic materials	4.150	mg	supplier	Wire	Gold	7440-57-5		4.150	mg	999980	2515	
Wire (Au)				supplier	Wire	Calcuim	7440-70-2		0.000	mg	20	0	
External Plating (Matte Sn)	Other inorganic materials	18.700	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		18.698	mg	999900	11332	
External Plating (Matte Sn)				supplier	Matte Sn	Impurities	-		0.002	mg	100	1	